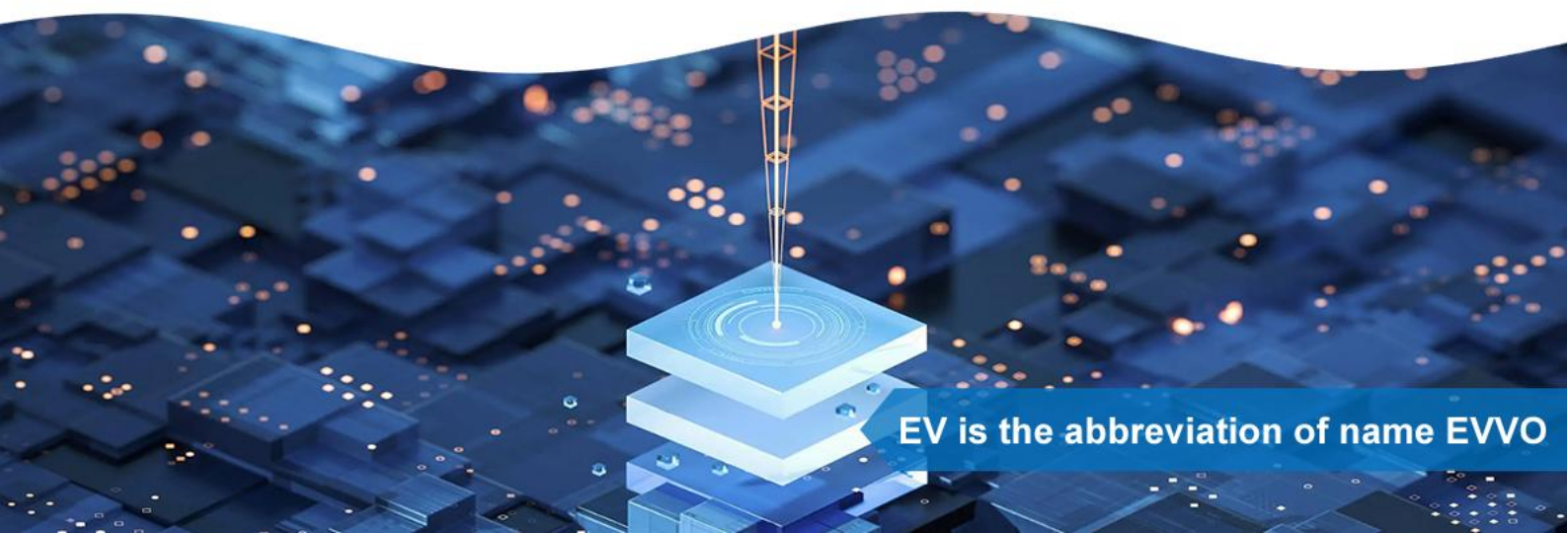
EVVOSEMI®
THINK CHANGE DO

ESD TVS MOS LDO Diode Sensor DC-DC

Product Specification

Domestic Part Number	AO6802
Overseas Part Number	AO6802
Equivalent Part Number	AO6802



EVVOSEMI®
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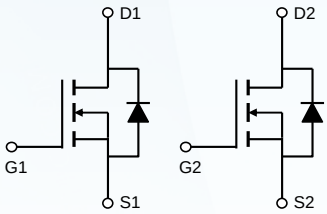
Dual N Channel MOSFET

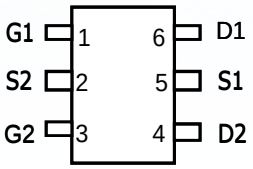
General Description

The AO6802 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications.



Product Summary

- $V_{DS\ (V)}$= 30V
- $R_{DS(ON)}$ < 50mΩ (V_{GS} = 10V)
- $R_{DS(ON)}$ < 70 mΩ (V_{GS} = 4.5V)



SOT23-6

Absolute Maximum Ratings T_A=25℃ unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_A=25℃	I_D	3.5	A
	T_A=70℃		3	
Pulsed Drain Current [C]		I_{DM}	20	
Power Dissipation [B]	T_A=25℃	P_D	1.15	W
	T_A=70℃		0.73	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	℃

Thermal Characteristics					
Parameter		**Symbol**	**Typ**	**Max**	**Units**
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	78	110	℃/W
Maximum Junction-to-Ambient [A D]	Steady-State		106	150	℃/W
Maximum Junction-to-Lead	Steady-State	$R_{\theta JL}$	64	80	℃/W

Dual N Channel MOSFET

Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250μA, V_{GS}=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			1	μA
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250μA	1.5	2	2.5	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=3.5A		40	50	mΩ
		V_{GS}=4.5V, I_D=2A		52	70	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=3.5A		12		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.79	1	V
I_S	Maximum Body-Diode Continuous Current				1.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		170	210	pF
C_{oss}	Output Capacitance			35		pF
C_{rss}	Reverse Transfer Capacitance			23		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	1.7	3.5	5.3	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=3.5A		4.05	5	nC
Q_g(4.5V)	Total Gate Charge			2	3	nC
Q_{gs}	Gate Source Charge			0.55		nC
Q_{gd}	Gate Drain Charge			1		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=4.2Ω, R_{GEN}=3Ω		4.5		ns
t_r	Turn-On Rise Time			1.5		ns
$t_{D(off)}$	Turn-Off DelayTime			18.5		ns
t_f	Turn-Off Fall Time			15.5		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=3.5A, dI/dt=100A/μs		7.5	10	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=3.5A, dI/dt=100A/μs		2.5		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25℃. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(MAX)}$=150℃, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150℃. Ratings are based on low frequency and duty cycles to keep initialT_J=25℃.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedence which is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(MAX)}$=150℃. The SOA curve provides a single pulse rating.

N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

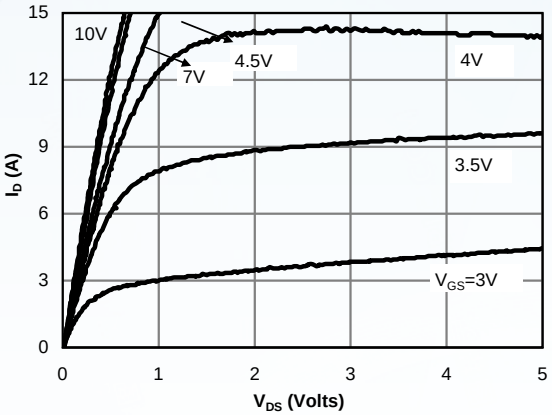


Fig 1: On-Region Characteristics (Note E)

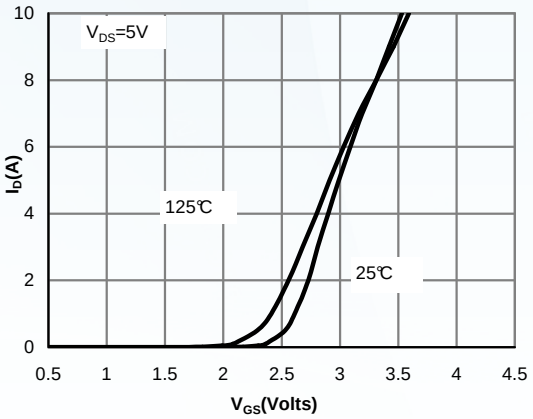


Figure 2: Transfer Characteristics (Note E)

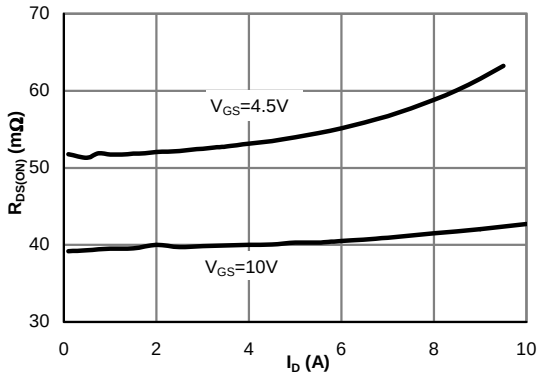


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

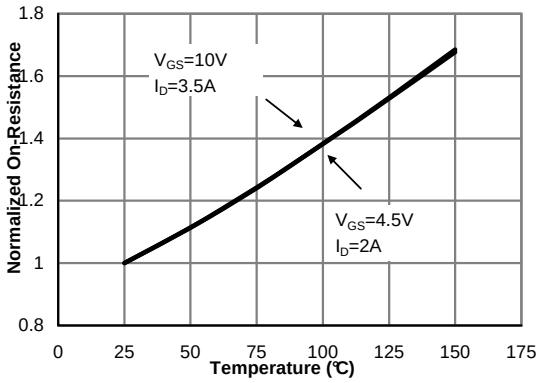


Figure 4: On-Resistance vs. Junction Temperature (Note E)

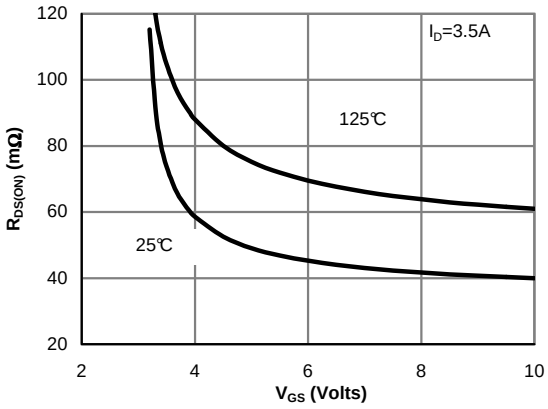


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

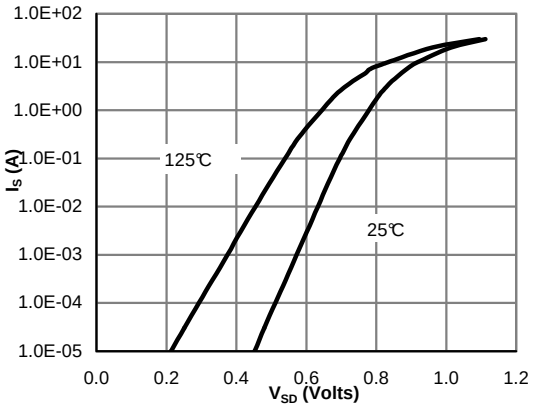


Figure 6: Body-Diode Characteristics (Note E)

N-Channel: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

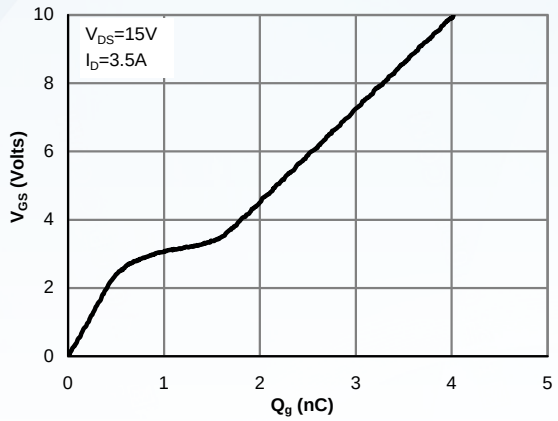


Figure 7: Gate-Charge Characteristics

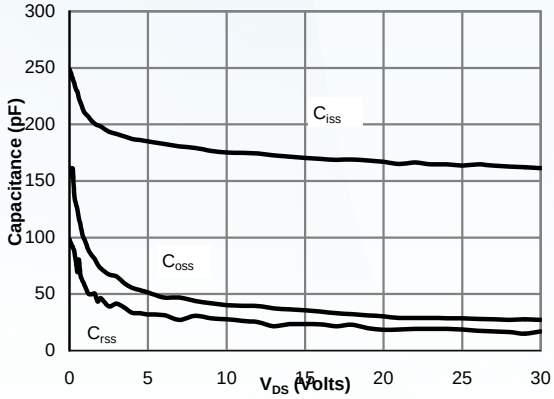


Figure 8: Capacitance Characteristics

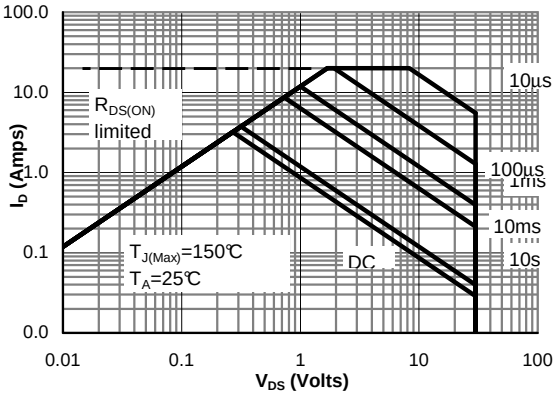


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

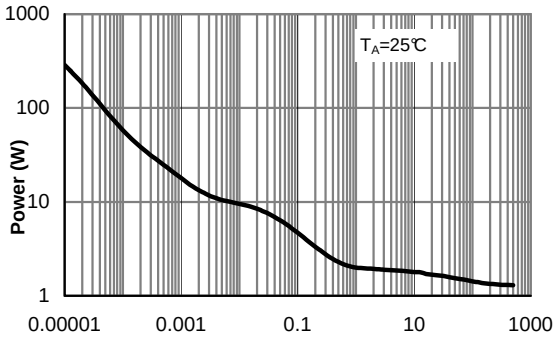


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

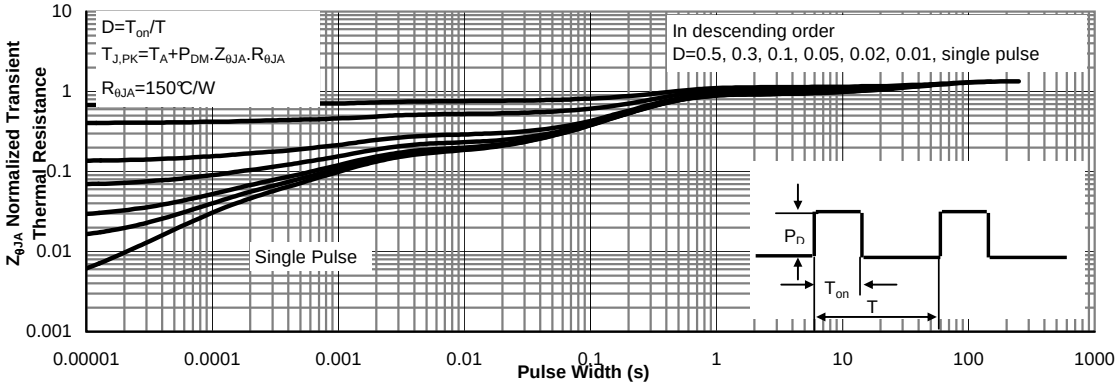
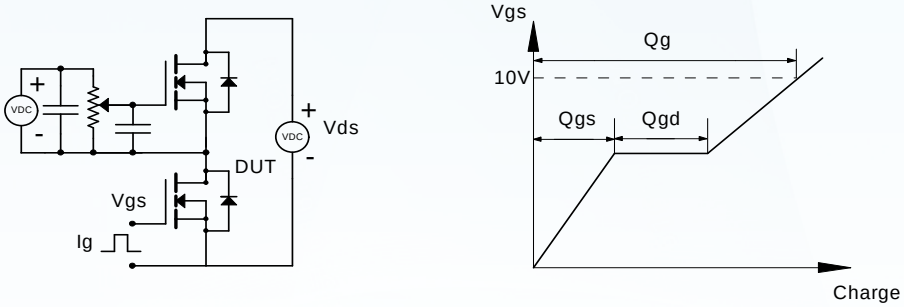
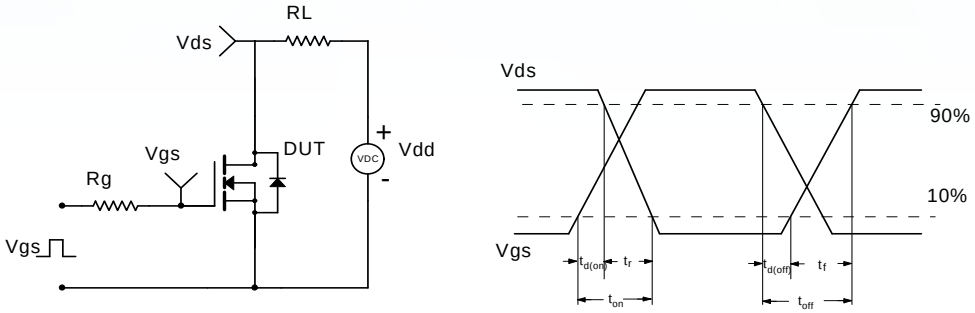


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

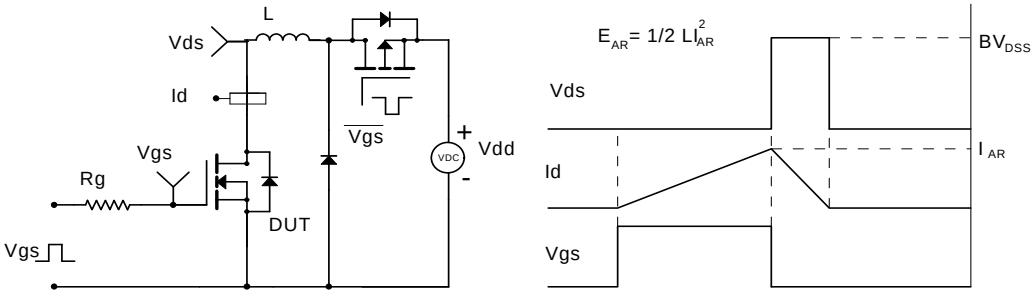
Gate Charge Test Circuit & Waveform



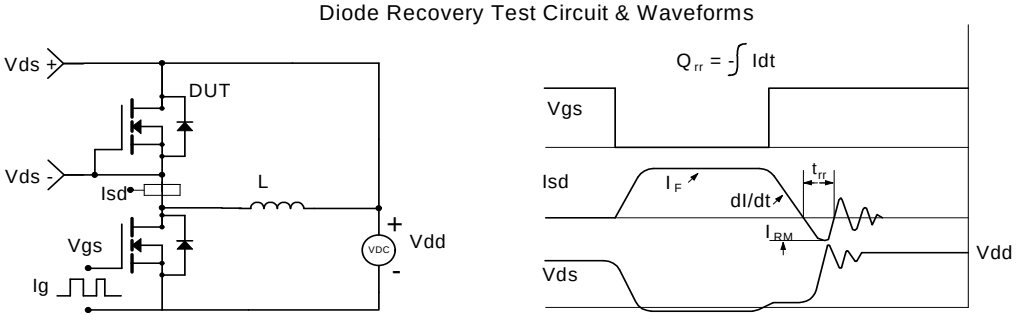
Resistive Switching Test Circuit & Waveforms



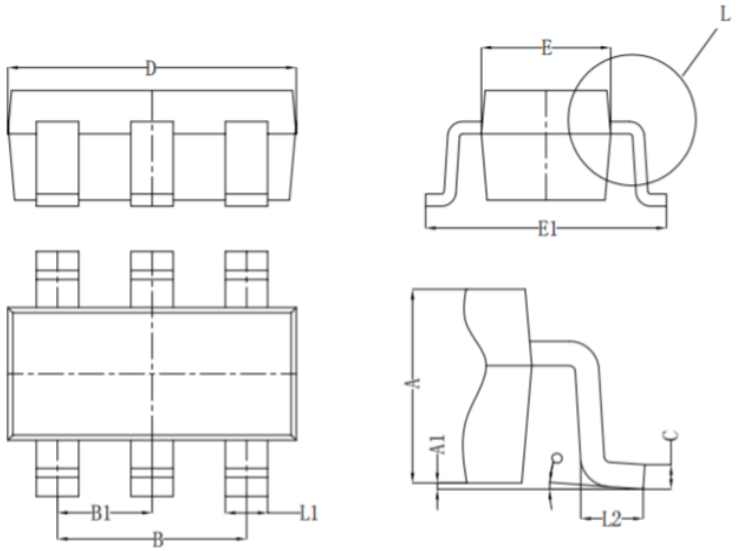
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



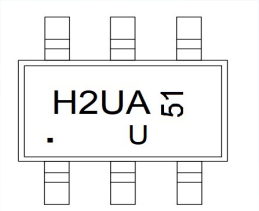
SOT23-6 PACKAGE OUTLIE DIMENSIONS



Detial L

Symbol	Dim in mm		
	Min	Nor	Max
A	1.050	1.100	1.150
A1	0.000	0.050	0.100
L1	0.300	0.400	0.500
C	0.100	0.150	0.200
D	2.820	2.920	3.020
E	1.500	1.600	1.700
E1	2.650	2.800	2.950
B	1.800	1.900	2.000
B1	0.950 TYP		
L2	0.300	0.450	0.600
θ	0°	4°	8°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
AO6802	SOT23-6	3000	Tape and reel

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